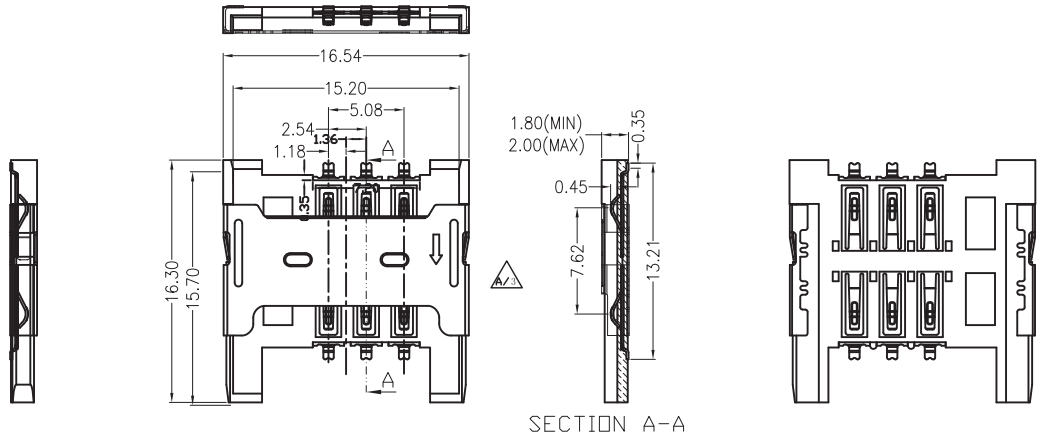
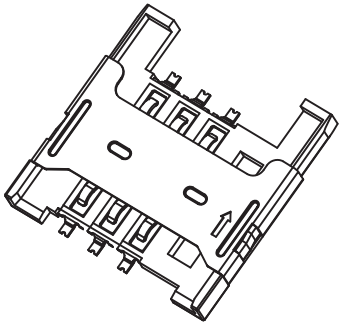
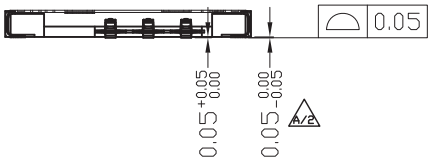
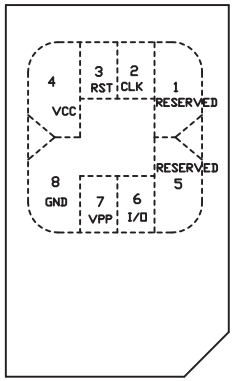
REV.	ECN	DESCRIPTION	MDF'D	APP'D	DATE
01		INITIAL DRAWING	Mark	Winds	2010/09/07

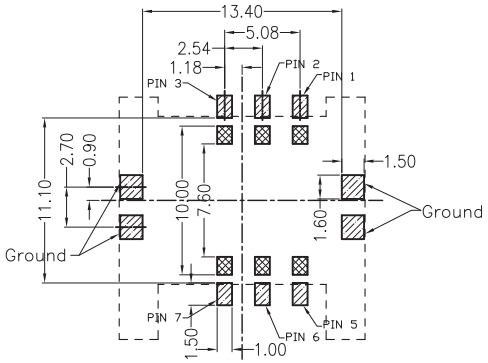








SIM CARD 2:1
TOP VIEW



RECOMMENDED P.C.B HOLE LAYOUT
COMPONENT SIDE VIEW(TOLERANCE: +/−0.05)

NOTES:
1. MATERIAL:
   HOUSING: HIGH TEMPERATURE THERMOPLASTIC UL94V_0,COLOR:BLACK.
   CONTACT: COPPER ALLOYS.
   COVER: COPPER ALLOYS OR STEEL.
2. PLATING:
   UNDERPLATE: NICKEL.
   CONTACT AREA: GOLD OVER NICKEL.
   SOLDER AREA: TIN OVER NICKEL.
3. MULTIMEDIA CARD COMPATIBLE

P/N # 708W6

	CUSTOMER SIGNATURE
APPROVED BY:	
DATE:	

Unit: mm	PROJECTION	Wellco T&C Co., Ltd.	
GENERAL TOLERANCES: (UNLESS SPECIFIED) 0 =±.38 0.0 =±.35 0.00 =±.25 0.000=±.15 0° =3° 0.0° =2°	D.R. 2010/09/07 Mark CH.K 2010/09/07 Albert APV.D 2010/09/07 Winds	TITLE: SIM CARD 6PIN 带挡型H1.8mm	PRODUCT NO. OR LAYOUT: SMAF3-EBS1-1101
		SCALE 1:1 / SIZE A4 / NO. DET. NO UCNR2XXXX0XX−0 / C	REV. 01 SH,T NO. 1 OF 1